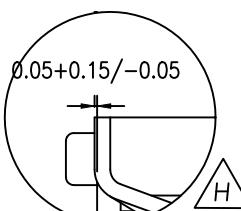
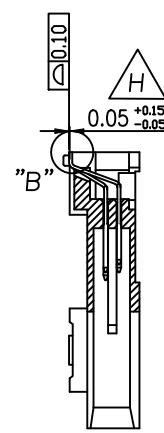
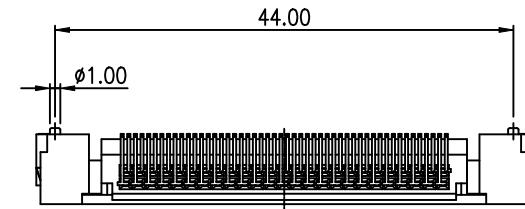


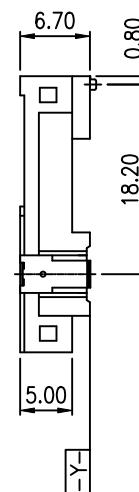
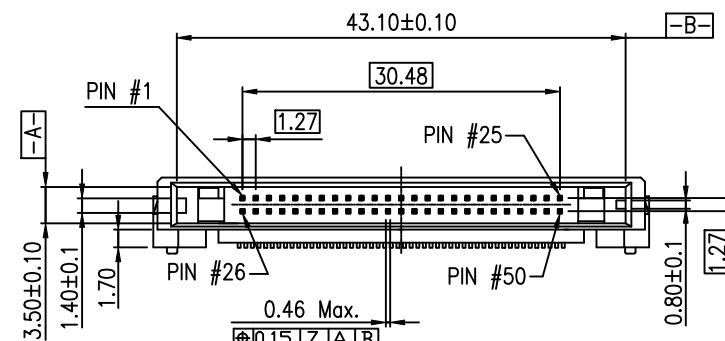
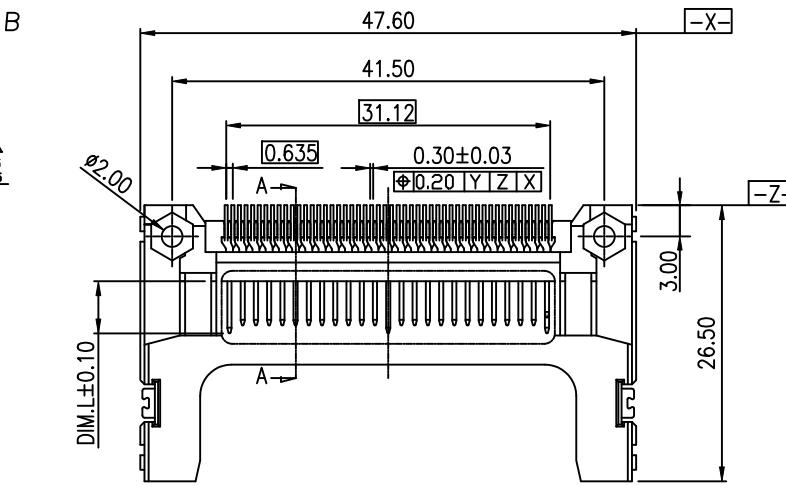
PRODUCT NO.  
10017963-XXXXX



DETAIL B

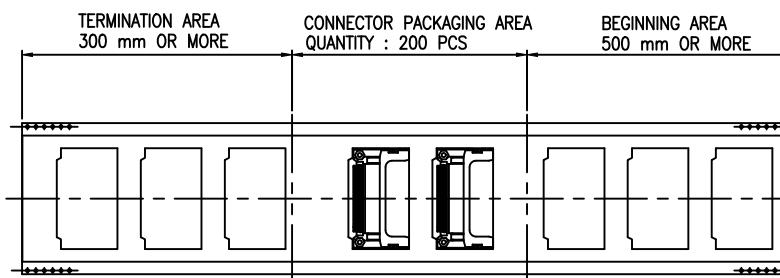
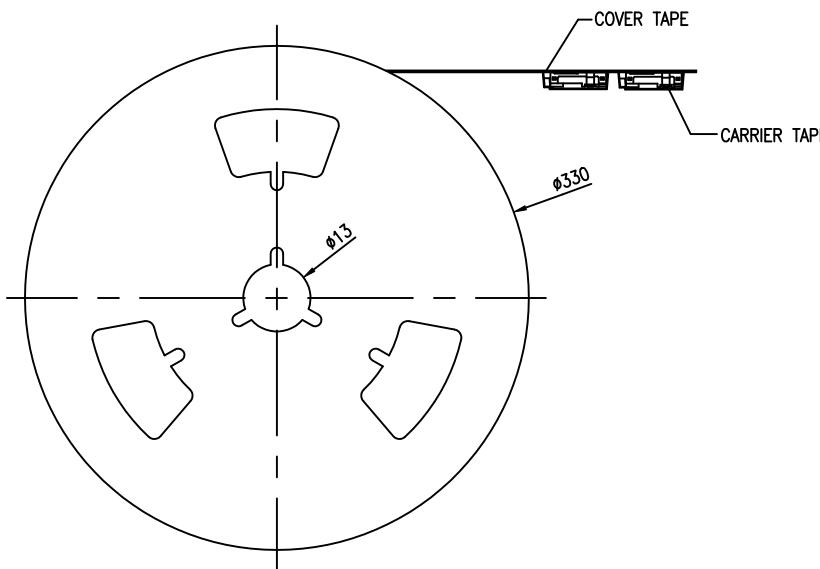
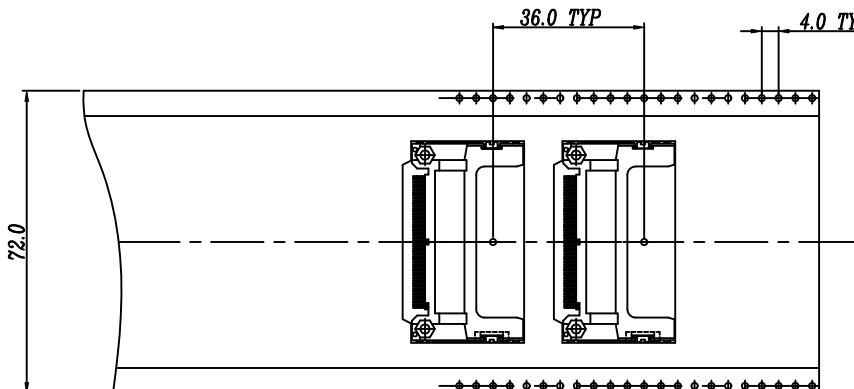
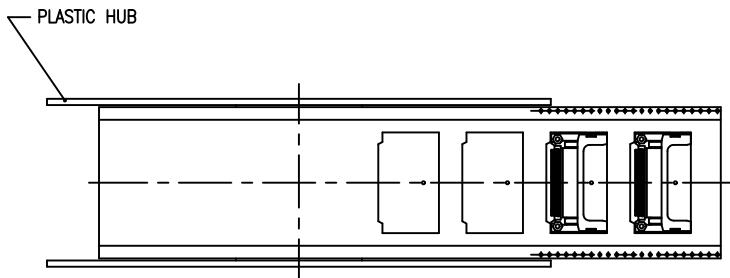


SECTION A-A



PIN TYPE	DIM.L±0.10	PIN NUMBER
DETECT	3.50	25,26
CENERAL	4.25	ALL OTHER PINS
POWER	5.00	1,13,38,50

mat'l. code				tolerances unless otherwise specified		CUSTOMER COPY	 www.fciconnect.com
ltr	ecn no	dr	date	linear	.X ± 0.30		
C	T03-0415	J.C	9/22/03	.XX ± 0.20		projection	title CF CARD HEADER TYPE 1
D	T05-0122	A.C	6/07/05	XXX ± 0.10			
E	T07-1119	WL	07/24/07	0° ± 2°			
F	T08-1014	WL	01/24/08	dr	JASON HSU 01/09/03	product family	code
G	T08-1023	WL	02/12/08	engr	JASON HSU 01/09/03	size	TWN
H	T10-0056	S.LIN	10'-5-06	chr	STERLING LIN 01/09/03	dwg no	
				appd	JAMES HSU 01/09/03	scale	
						A4	10017963
sheet index		revision	H H H				
sheet			1 2 3				



COMPOSITION OF PACKAGING

NOTES:

1. CARRIER TAPE : PS , t=0.35mm.
2. COVER TAPE : PE.
3. PLASTIC HUB : PS.

## NOTES:

## 1. Materials:

Housing: High Temperature Thermoplastic , UL94V-0, Color/Natural.  
 Contact: Copper Alloy.  
 Solderable Holddown: Copper Alloy.

## 2. Specification:

Product Spec: GS-12-240.  
 Packaging Spec: GS-14-1010.

## 3. Tin/Lead Plating Spec:

Contact: Under Plated 50 $\mu$ " Min Nickel All Over,  
 100 $\mu$ " Min Tin/Lead in Solder Tail Area,  
 Selective Gold Plating in Contact Area.  
 Solderable Holddown: Under Plated 50 $\mu$ " Min Nickel,  
 Plated 100 $\mu$ "Min Tin/Lead All Over.

## 4. Lead-Free Plating Spec:

Contact: Under Plated 50 $\mu$ " Min Nickel All Over,  
 100 $\mu$ " Min Pure Matte Tin in Solder Tail Area,  
 Selective Gold Plating in Contact Area.  
 Solderable Holddown: Under Plated 50 $\mu$ " Min Nickel,  
 Plated 100 $\mu$ "Min Pure Matte Tin All Over.

5. The Housing Will Withstand Exposure to 260°C Peak  
 Temperature For 10 Seconds In A Convection, IR Or Vaper  
 Phase Reflow Oven.

6. This Product (10017963-XXXXXXLF) Meets the European Union  
 Directive as Described in GS-22-008, Sub Clause 3.1.  
 (2002/95/EC).

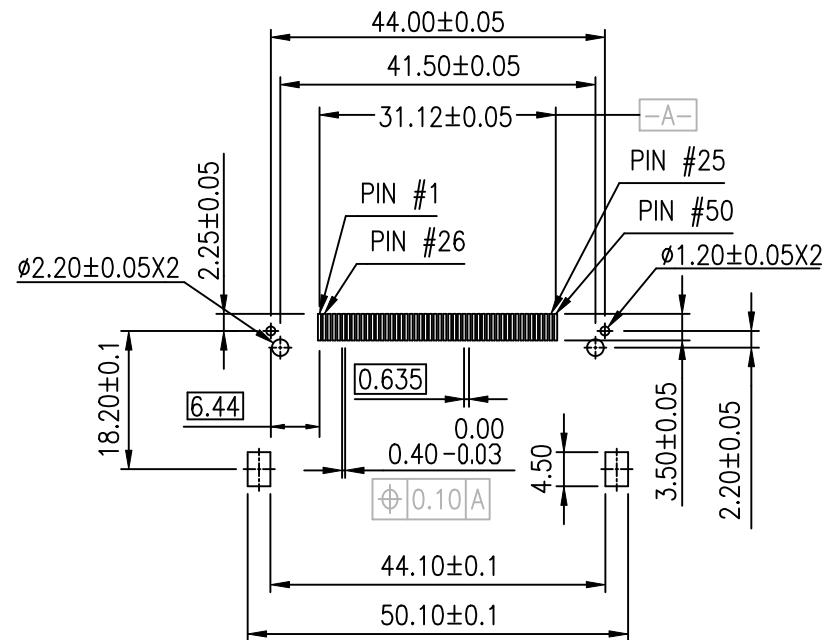
## 7. PART NUMBER DESCRIPTION:

10017963-X050XX

LEAD-FREE PLATING OPTION  
 BLANK: TIN/LEAD PLATING(SEE NOTE3).  
 LF: LEAD-FREE PLATING(SEE NOTE4).

PACKAGING  
 BLANK: PVC TRAY.  
 T: TAPE & REEL.

CONTACT AREA PLATING:  
 D: 15 $\mu$ " GOLD.  
 E: 30 $\mu$ " GOLD.



P.C.B Layout

mat'l. code				tolerances unless otherwise specified		CUSTOMER COPY	FCI		www.fciconnect.com
ltr	ecn no	dr	date	linear	angles		projection	title	
H				.XX ± 0.20				CF CARD HEADER	
				XXX ± 0.10				TYPE 1	
				0° ± 2°					
		dr	JASON HSU 01/09/03		MM		product family		code
		engr	JASON HSU 01/09/03				size	TWN	
		chr	STERLING LIN 01/09/03		scale		dwg no		
		appd	JAMES HSU 01/09/03						sheet
		sheet index	revision sheet						3 of